

2. 7th GI/GMM/ITG workshop, February 3, 2009, Ulm, DE by Coventor: introduction of EDA-compatible methodology for design and simulation of MEMS with IC

3. New Materials Forum, March 5-6, 2009, Valencia, ES by Process Relations


5. May 11, 2009, MikroMedia No. 44: “Design solution for MEMS and IC products” and "Process Relations signs up AMO for its XperiDesk process management software”

6. May 18, 2009, 2. Article in EETimes: Turnkey environment allows MEMS/IC co-design, co-verification and corresponding movie related to Coventor-Cadence Partnership

7. CDN Live 2009 Conference, May 18-20, 2009, Munich, DE: presentation „MEMS-IC Common Platform” by Gunar Lorenz, Coventor awarded with the „Best Paper Award”


12. COMS, August 30-September 3, 2009, Copenhagen, Denmark: presentation by PR


17. 15th International Workshop on Thermal investigations of ICs and Systems, Leuven, Belgium October 7-9, 2009: poster, conference proceedings, submission for Microelectronic Journal: Thermo-Mechanical Reliability Loop In Device Modeling by Tomasz Bieniek, ITE

18. 4th International Conference on Advanced Research and Rapid Prototyping, Leiria, Portugal, October 6 – 10, 2009, Presentation: A holistic approach for customer-oriented product engineering of micro devices, Kai Hahn, USI

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